Amendments to the Specification:

Please replace the paragraph beginning on page 2, line 30 with the following rewritten paragraph:

-- FIG. 2 is a representative diagram showing a test system for detecting hopping pixel defects in image sensors. A CCD image sensor 10 is seated on a heat plate 12 of which temperature is controlled by a temperature control unit 14. The temperature of the plate 12 is typically adjusted so that the CCD image sensor 10 when operated will be at temperature in the range of about 20 to 80°C. As previously discussed, it has been determined that by heating the CCD image sensor 10 under test, the hopping pixel defects will become more pronounced and occur more frequently. The system has power supplies and pulse generating circuits 32 controlled by a central processing unit (CPU) 20 to support CCD DC bias and clock driver circuits 34. The clock driver circuits 34 operates the CCD in a well known fashion under the control of the pulse generating circuits 32. The CCD output signals are digitized and synchronized to display results on output device 48 (commonly a cathode ray tube (CRT)) through an A/D converter 42, a frame grabber 44 and its internal memory 46. A test algorithm 22 (will be discussed later) is fed into the CPU 20 at the beginning of the test and the CPU 20 controls the operating conditions of the CCD image sensor 10 and starts the test. The CPU 20 calculates the test results in its internal memory 46 according to the test algorithm 22 and sends the final results to output device 48. The test is finished by mapping detected hopping pixel defects in the CCD image sensor 10 to the output ~~deviee 46~~ device 48. See FIGS. 4a-e. --